

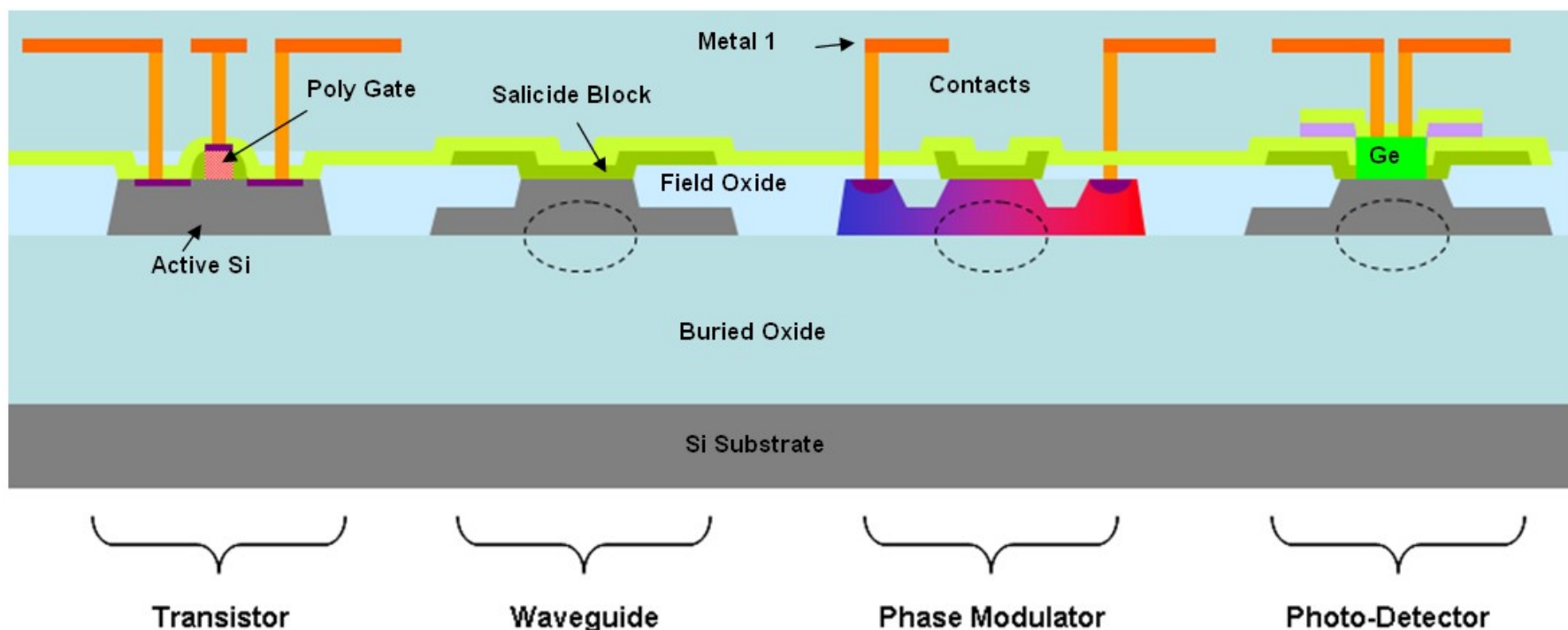
SPE

Silicon Photonics Experiment

- Costruzione e test di un dimostratore di un sistema di trasmissione ad alta banda passante (~10 Gbps) basato su Silicon Photonics
- Durata del progetto: 2 anni
- Interesse del CERN (progetto congiunto CERN-INTEL)

Si-Photonics, a paradigm changing technology?

- Si
 - is an excellent optical material with high refractive index
 - Is widely available in high quality grade
 - Can be processed with extreme precision using deep submicron CMOS processing techniques
- So, why not build a photonic circuit in a CMOS Si-wafer?



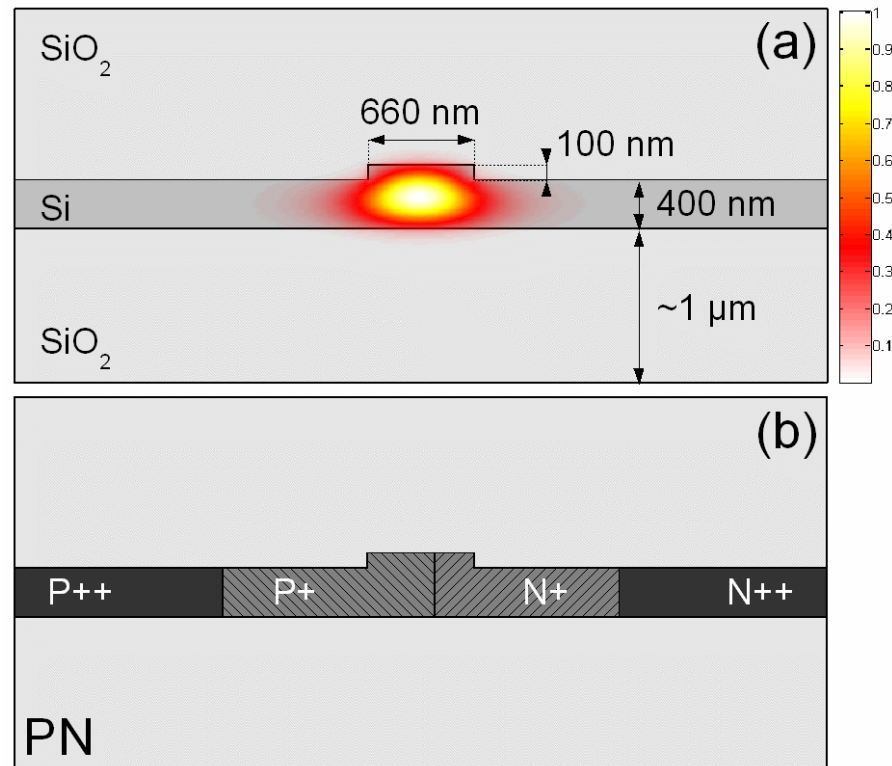
Optical modulation within CMOS photonic IC

Modulating the free carrier concentrations:

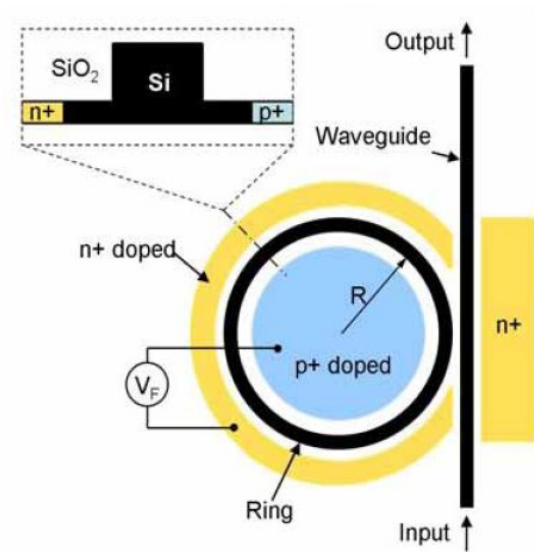
$$\Delta n = -8,8 \cdot 10^{-22} \Delta N - 8,5 \cdot 10^{-18} \Delta P^{0,8}$$

$$\Delta \alpha = 8,5 \cdot 10^{-18} \Delta N + 6,0 \cdot 10^{-18} \Delta P$$

at $\lambda = 1.55 \mu\text{m}$

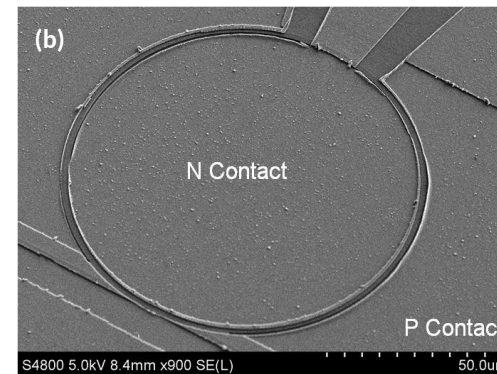
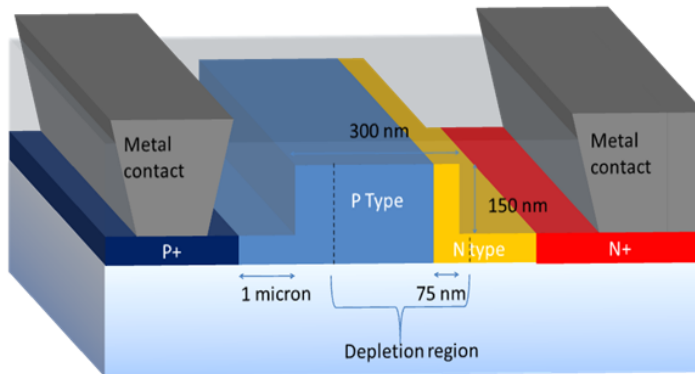


Carrier injection (es del ring resonator)

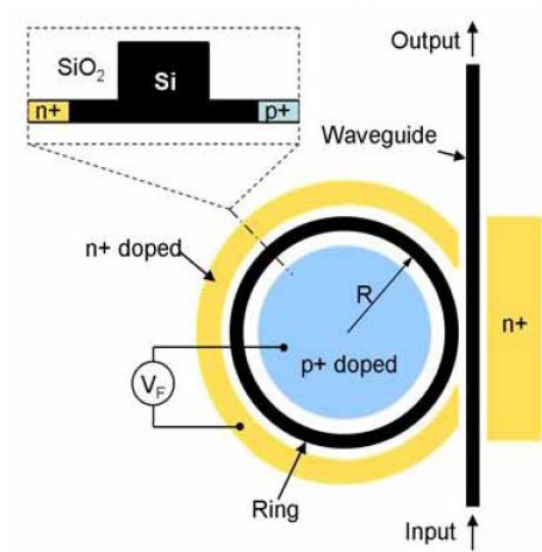


Carrier depletion (es del ring resonator)

PN diode

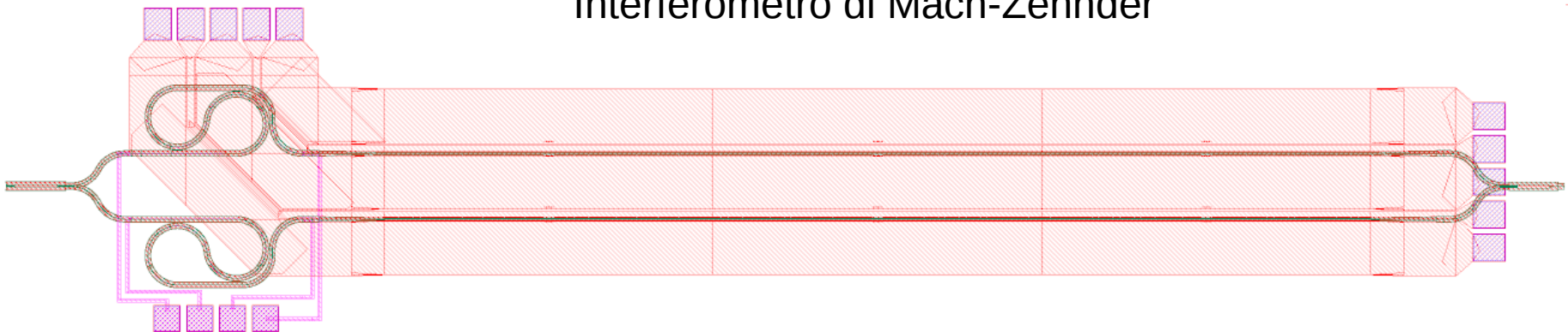


I modulatori



Ring resonator

Interferometro di Mach-Zehnder

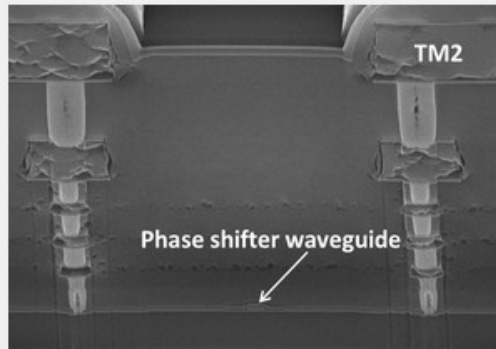


IHP technology @ Europractice

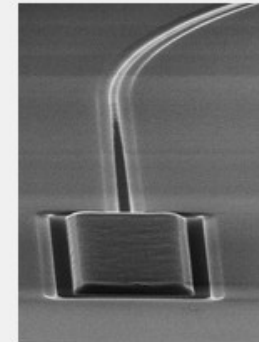
- Technology
 - Imec - Passives
 - Imec - ISIPP25G+
 - LETI-Passives with Heaters
 - IHP-Passives Ge photodiode
- Runschedule & Pricing
 - Runschedule
 - Pricing
 - NDA-DKLA
- Info
 - Design info
 - Practical info
 - NDA-DKLA
- Photonics Packaging
 - Technology description
 - Packaging Prices

Basic characteristics

- Passive waveguide structures
- Three etching levels (220nm, 70nm, 120nm)
- Two waveguide doping levels
- 5 metal layer backend (3x metal + 2x top metal)
- Modulator building block
 - 15GHz bandwidth
 - 15dB insertion loss
 - $V_{\pi}=6V$
 - 5mm long
- Germanium photodiode building block
 - 40GHz bandwidth@-2V
 - 0.6A/W responsivity
- Optional localized backside etching
- 248nm DUV stepper lithography



Cross section of a modulator waveguide



Germanium photodiode without backend

Indicative performance

Device	Specification	
Strip waveguide	Loss	<3dB/cm
Rib waveguide (70nm etch)	Loss	<1.5dB/cm
Rib waveguide (120nm etch)	Loss	<2dB/cm
1D Fiber coupler (14°, TE)	Insertion loss	<5dB

2016 price and schedule (Europractice)

- IHP SG25 PIC: 1300 Euro / mm²
- IHP SG25H_EPIC: 4550 Euro / mm²
- IHP SG25H4: 3750 Euro / mm²

IHP	J	F	M	A	M	J	J	A	S	O	N	D
IHP SGB25V 0.25μ SiGe:C Ft=75GHz@BVCEO 2.4V	25							1		31		
IHP SGB25VGD 0.25μ SiGe:C Ft=75GHz@BVCEO 2.4V + RF HV-LDMOS GD-Module 22V	25									31		
IHP SG25H1 0.25μ SiGe:C Ft/Fmax=190GHz/220GHz 5M/MIM	25				2			1				
IHP SG25H3P 0.25μ Complementary SiGe:C Ft/Fmax (nnp)110/180GHz / (pnp)90/120GHz 5M/MIM										31		
IHP SG25H3 0.25μ SiGe:C Ft/Fmax=110/180GHz 5M/MIM	25				2					31		
IHP SG25H4 0.25μ SiGe:C Ft/Fmax=200/220GHz 5M/MIM	25				2			1		31		
SG25H_EPIC (based on SG25H4)										31		
IHP SG13S SiGe:C Bipolar/Analog/CMOS Ft/Fmax= 250/300GHz 7M/MIM			29					29				5
IHP SG13C SiGe:C CMOS 7M/MIM			29					29				5
IHP SG13G2 SiGe:C Bipolar/Analog Ft/Fmax=300/500GHz 7M/MIM			29					29				5
IHP SG25 PIC (Photonics, Ge Photo-diode, BEOL)						30						

Bumping available for all IHP technologies with extra charge, limited to 200 bumps

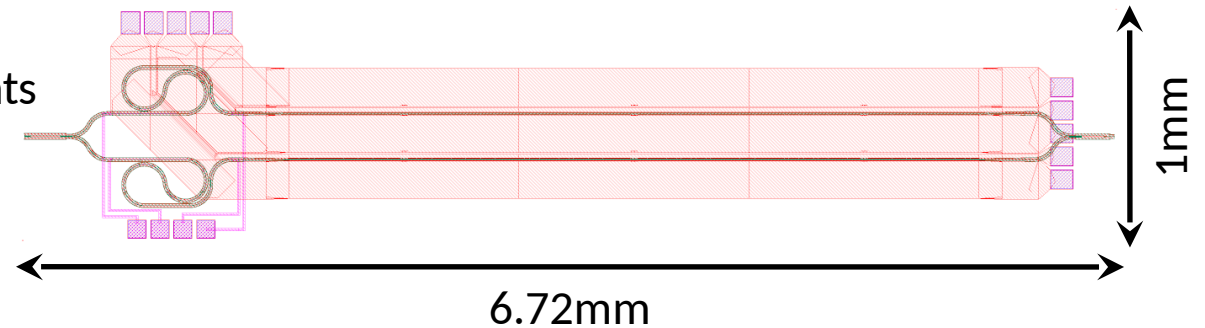
Layout size (MZ standard)

Overall estimation

At least: 8.48mm × 1.11mm

Most inner modulator part

- 5mm phase shifter
- Thermal heating tuning elements
- Travelling wave electrode
- 1 port left side
- 2 ports right side

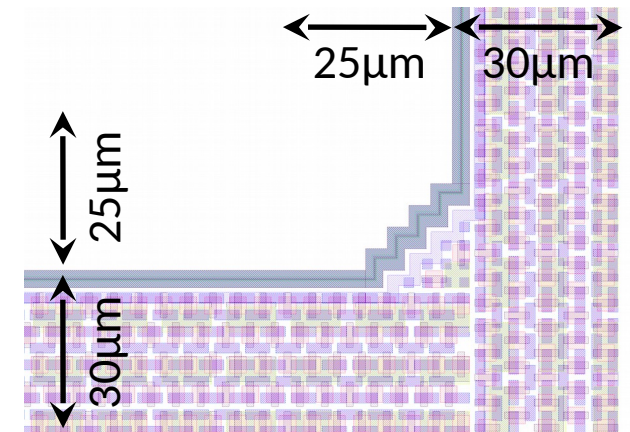


In- and output

- Standard grating coupler + taper = 0.75mm
- SBends for separation at right side $\leq 0.16\text{mm}$
- worst case +1.66mm in length

Seal ring

- Recommended inner distance to sealring $\geq 25\mu\text{m}$
- Sealring width (including outside filler area) = $35\mu\text{m}$

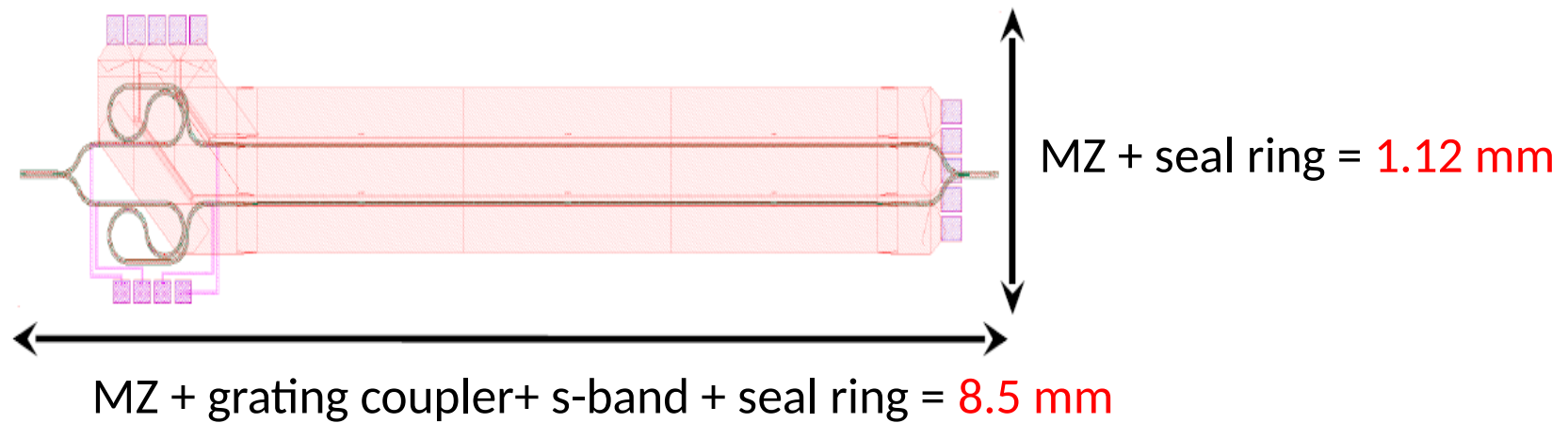


~10 mm² per la sola parte fotonica senza considerare l'elettronica @ 4550Euro+IVA / mm²: IMPOSSIBILE → dobbiamo ridurre le dimensioni del modulatore

Proposal

- **May 2017** PIC run (@ 1300Euro+IVA/mm²): “large” photonics test chip: 2 MZ interferometers + 2 ring resonator
- **October 2017** EPIC run (@ 4550Euro+IVA/mm²): 1 “small” MZI OR 1 ring res. + preliminary electronics
- May 2018 PIC run (@ 1300Euro+IVA/mm²): ?
- May 2018 only uE run (@ 3750Euro+IVA/mm²): ?
- **October 2018** EPIC run (@ 4550Euro+IVA/mm²): “final” demonstrator

Mach-Zehnder -standard version



MZ standard version

A=9.52mm²

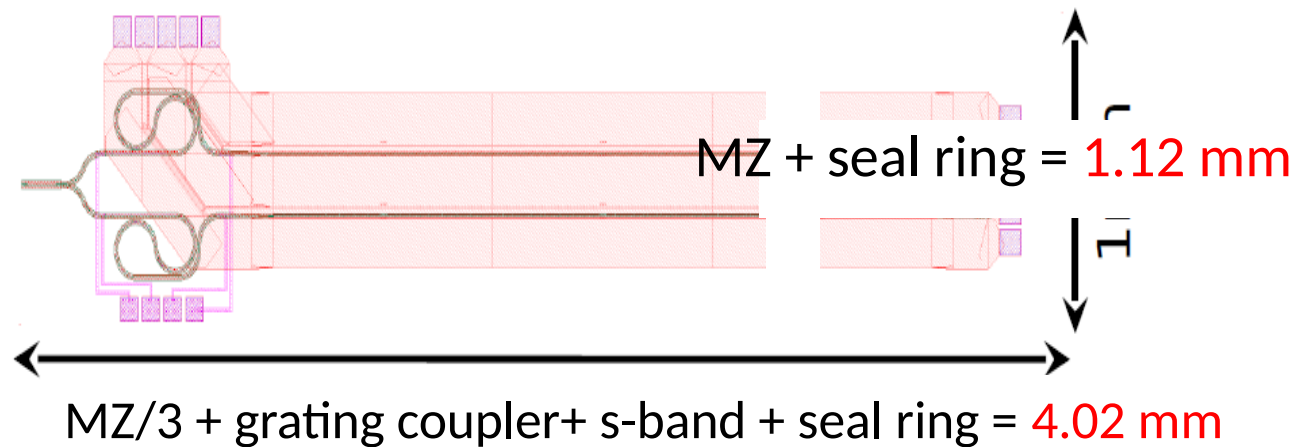
□ 12376 Euro

(PIC run)

□ 43316 Euro

(EPIC run)

Mach-Zehnder -smaller version



MZ smaller version

$$A=4.51\text{mm}^2$$

⇒ 5863 Euro

(PIC run)

⇒ 20520.5 Euro

(EPIC run)

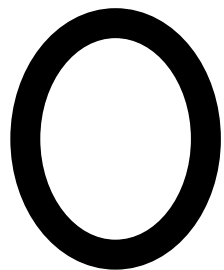
Ring Resonator

Version 1

$A=0.684\text{mm}^2$

≡ 889.2 Euro
(PIC run)

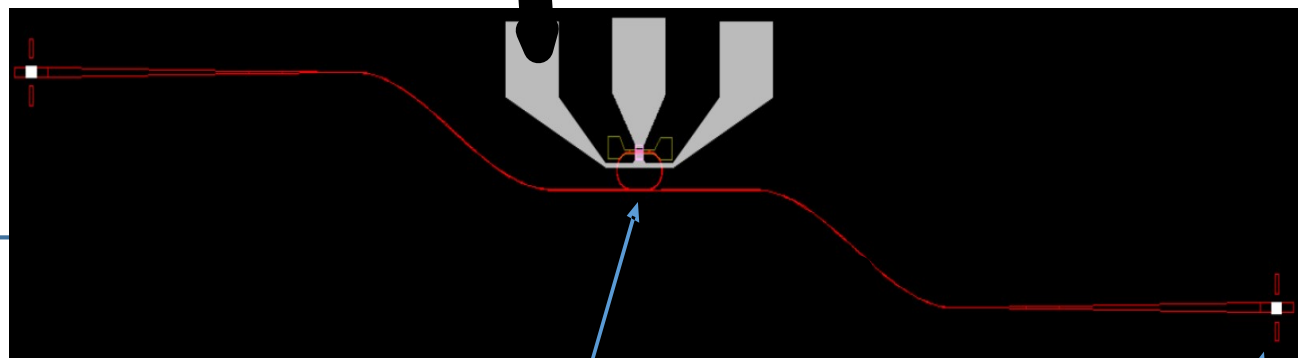
≡ 3112.2 Euro
(EPIC run)



RR + grating coupler + s-band
+ seal ring = **1.9 mm**

RR + seal ring
= **0.36 mm**

GSG electrodes



Ring Resonator

s-band

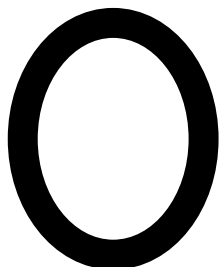
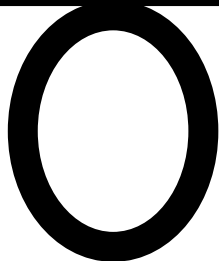
Grating coupler
with taper

Version 2

$A=0.874\text{mm}^2$

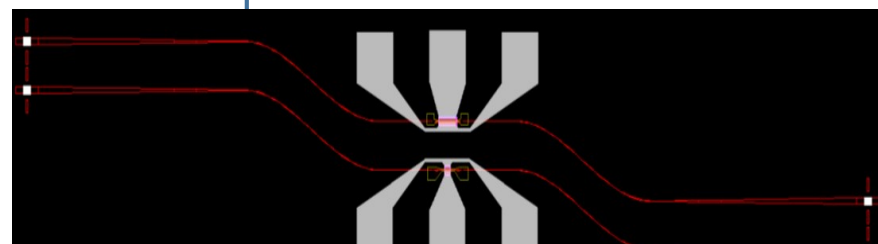
≡ 1136.2 Euro
(PIC run)

≡ 3976.7 Euro
(EPIC run)

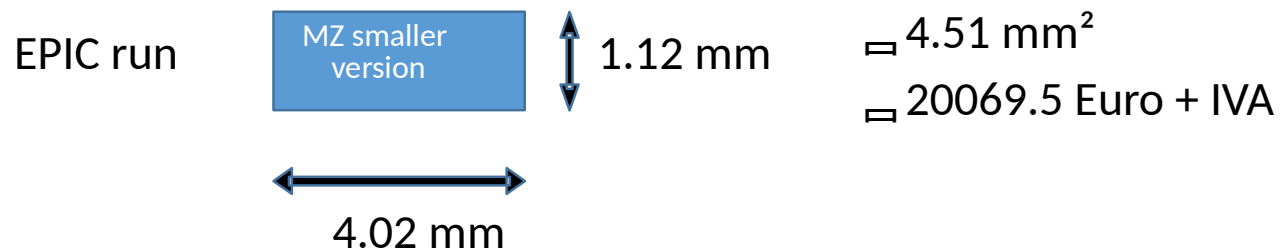
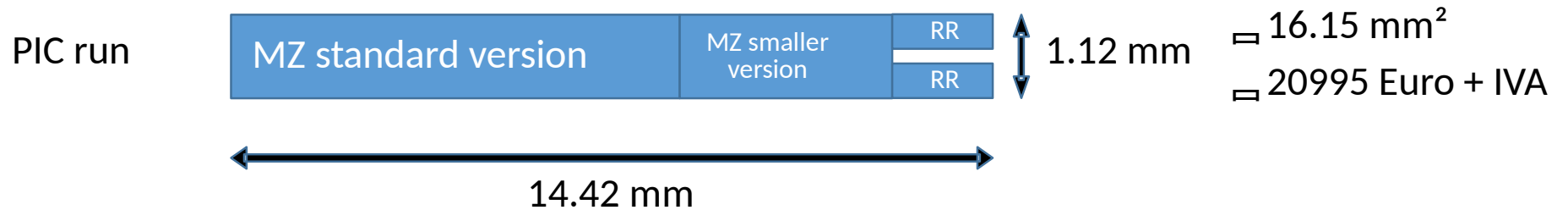


RR + seal ring
= **0.46 mm**

RR + g. coupler + s-band + s. ring = **1.9 mm**



Chip size estimation



Richieste economiche 2017

- 1 run di fonderia (PIC) 25 kEuro + packaging 3 kEuro (consumo)
- 1 run di fonderia (EPIC) 30 kEuro + packaging 3 kEuro (consumo SJ)
- 1 laser @ 1550 nm + photodetector 30 kEuro (inventario SJ)
- Produzione PCB 3 kEuro (consumo)
- Minuteria da laboratorio 1 kEuro (consumo)
- Microprobes 5 kEuro (inventario SJ)
- Missioni 5 kEuro

Anagrafica 2017

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7 > CSN V > SPE > Roma II > Modulo EC/EN 7

SPE
Modulo EC/EN 7

A cura di: A

Ricercatori						
	Nome	Età	Contratto	Qualifica	Aff.	%
1	De Matteis Fabio				CSN V	40
2	Proposito Paolo				CSN V	40
3	Salamon Andrea		Dipendente	Ricercatore	CSN I	40
Numero Totale Ricercatori					3	FTE: 1.2

Tecnologi						
	Nome	Età	Contratto	Qualifica	Aff.	%
1	Bonaiuto Vincenzo		Associato	Prof. Associato	CSN I	30
2	Sargeni Fausto		Associato	Prof. Associato	CSN I	30
Numero Totale Tecnologi					2	FTE: 0.6

Tecnici						
	Nome	Età	Contratto	Qualifica	Aff.	%
1	Badoni Davide		Dipendente	Collaboratore Tecnico E.R.	CSN I	20
Numero Totale Tecnici					1	FTE: 0.2

Annotazioni

Mauro Casalbani – Professore Ordinario – Dip. Ing. Industriale
Patrick Steglich – Dottorando – Dip. Ing. Industriale

40%
40%

Set

Osservazioni del direttore

Mod. EC/EN7

[Visualizza per la stampa](#)